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INDEX OF PAPERS AND PRESENTERS

SESSION W1A – PRINTED ELECTRONICS

[Processing of printed silver patterns on an ETFE substrate1](#)

Riikka Mikkonen, Tampere University of Technology, Finland

[Towards Electronics Everywhere – Hybrid Integration Case Study \(Abstract\)8](#)

Antti Kemppainen, VTT, Finland

SESSION W1B – QUALITY ASSURANCE

[Contribution to non-destructive inspection of power semiconductor assemblies by stimulating a lateral heat flow9](#)

Michael Schaulin, Technische Universität Dresden, Germany

[Quality assurance of encapsulation architecture, including subsequent washing process for permanently mounted wearable sensors15](#)

Heléne Karlsson, Swerea IVF AB, Sweden

SESSION W2 – REALIABILITY

[Influence of Voids on the Reliability of Power Module Interconnections \(Abstract\)25](#)

Jussi Putaala, University of Oulu, Finland

[Overcoming Human Factors by Utilizing Design Modeling to Improve High Reliability Electronics26](#)

Natalie Hernandez, DfR Solutions, USA

[Plastic QFN Packaging for Space Applications31](#)

Ignas van Dommelen, Sencio BV, The Netherlands

SESSION W3A – NEW MATERIALS

[Reliability challenges in Cu-Sn micro-connects \(Abstract\)37](#)

Glenn Ross, Aalto University, Finland

[Screen Printed Conductive Composites with Reduced Graphene Oxide and Silver39](#)

Man Song, Uppsala University, Sweden

[Electrical and Thermal Conduction of Isotropic Conductive Adhesive based on Novel Conductive Particles44](#)

Helge Kristiansen, Conpart AS, Norway

[Glasses and Glass Ceramics for Electronic Applications in Semiconductor Packages and 5G Mobile Networks \(Abstract\)49](#)
Martin Letz, SCHOTT AG, Germany

SESSION W3B – APPLICATIONS

[Structured metallization on glass: A comparative study of resonance and propagation characteristics at 24GHz \(Abstract\)50](#)
Martin Letz, SCHOTT AG, Germany

[Improving the performance of advertising LED displays by in-mould integration52](#)
Eveliina Juntunen, VTT, Finland

[Neurological active implants: challenges and opportunities \(Presentation\)N/A](#)
Claude Clément, Wyss Center for Bio and Neuro-engineering, Switzerland

[Reliability of Conductive Adhesives for IoT57](#)
Daniel Nilsen Wright, SINTEF, Norway

SESSION T1 – MANUFACTURING

[Component Packages for IMSE™ \(Injection Molded Structural Electronics\)61](#)
Outi Rusanen, TactoTek, Finland

[Solutions for thin and tiny dies with high die strength and for thinning WLCSP and eWLB wafers \(Presentation\)66](#)
Christoph Epple, DISCO HI-TEC EUROPE GmbH, Germany

[Quality assurance of encapsulation architecture, including subsequent washing process for permanently mounted wearable sensors74](#)
Dag Andersson, Swerea IVF AB, Sweden

SESSION T2A – CERAMICS

[Current Situation with Ultra-Low Temperature Co-fired Ceramics \(ULTCC\) \(Abstract\)84](#)
Heli Jantunen, Oulu University, Finland

[Overload-proof LTCC differential pressure sensors for high temperature applications85](#)
Adrian Goldberg, Fraunhofer Institute for Ceramic Technologies and Systems IKTS, Germany

[LTCC Resistors – The Influence of Production Conditions on the Absolute Value and its Reproducibility91](#)
Peter Uhlig, IMST GmbH, Germany

SESSION T2B – CORROSION & HUMIDITY

[*Corrosion Reliability of Lead-Free Solder Systems Used in Electronics97*](#)

Feng Li, Technical University of Denmark, Denmark

[*Water film formation on the PCBA surface and failure occurrence in electronics102*](#)

Kamila Piotrowska, Technical University of Denmark, Denmark

[*Humidity effects on conformal coated electronics for harsh environments \(Abstract\)107*](#)

Morten Stendahl Jellesen, Technical University of Denmark, Denmark

SESSION T3 – ADVANCED PACKAGING

[*Multifunctional MMICs – Key Enabler for Future AESA Panel Arrays108*](#)

Martin Oppermann, HENSOLDT Sensors GmbH, Germany

[*Wafer-level Re-Packaging of Commercial Components for Miniaturization and Embedding112*](#)

Jens Müller, Technische Universität Ilmenau, Germany

[*A Printed Electroluminescent Matrix Display: Implementation Details and Technical Solutions117*](#)

Artem Ivanov, Landshut University of Applied Sciences, Germany

[*Reliability study on high thermally conductive graphene film as heat spreader in electronics cooling applications126*](#)

Amos Nkansah, SHT Smart High-Tech AB, Sweden